

IN THE UNITED STATES DESIGNATED/ELECTED OFFICE

International Application No. : PCT/EP00/06314
International Filing Date : 5 JULY 2000
Priority Date(s) Claimed : 28 JULY 1999
Applicant(s) (DO/EO/US) : ZIELINSKI, Claudia, et al.
Title: ETCHING SOLUTION, CONTAINING HYDROFLUORIC ACID

#74
9/30/02
MW.

PRELIMINARY AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

SIR:

Prior to calculating the national fee, and prior to examination in the National Phase of the above-identified International application, please amend as follows:

IN THE CLAIMS:

- A1
6. (Amended) Etching solutions according to Claim 1, comprising water in an amount of from 1 to 20% by weight. B
7. (Amended) Etching solutions according to Claim 1, comprising a mixture of high-purity individual components.
8. (Amended) Use of the etching solutions according to Claim 1 for the selective etching of doped silicate layers.